

IN THE ABSTRACT

Please amend the Abstract on pages 45-46 as follows.

~~Herein is disclosed thermosetting resin composition comprising an epoxy resin (Component (A)) which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, and a resin (Component (B)) which has a number average molecular weight of 800 to 35,000, an average functional group number of more than 2 per one molecule, and a functional group equivalent of 150 to 2,000 g/mol, which has one or more functional groups selected from amino group, carboxyl group, acid anhydride group, mercapto group, hydroxyl group, isocyanate group and hydrazide group, and no blocked carboxyl group, and which may have a polybutadiene or hydrogenated polybutadiene skeleton, wherein the ratio of the Component (B) to the Component (A) is from 0.5 to 2.0 in terms of the overall equivalent number of the functional group(s) of Component (B) capable of reacting with the epoxy group of the Component (A) to the overall equivalent number of the epoxy group of the Component (A), whose cured products are adjusted in crosslinking density by using an epoxy resin whose molecular weight and functional group number per one molecule are restricted to a certain range, as a component of the above thermosetting resin composition. This A thermosetting resin composition that is useful as an epoxy resin-based overcoating agent for flexible circuit boards or for film carriers for the TAB method, and the like, providing basic properties required of general insulation protective films, since the cured coated films are excellent in adhesiveness, electric insulation property, chemical resistance, thermal resistance, and the like, reduced in warp caused by cure shrinkage, and excellent in flexibility.~~

ABSTRACT

A thermosetting resin composition that is useful as an epoxy resin-based overcoating agent for flexible circuit boards or for film carriers for the TAB method, and the like, providing basic properties required of general insulation protective films, since the cured coated films are excellent in adhesiveness, electric insulation property, chemical resistance, thermal resistance, and the like, reduced in warp caused by cure shrinkage, and excellent in flexibility.

SUPPORT FOR THE AMENDMENT

Claims 3-5 are cancelled. Claims 6-10 are added.

Support for the Amendment to the Specification corrects typographical, clerical, and translational errors.

Support for the change of “700” to “300” on pages 7-8 (two occurrences) is found on p. 42, line 24 and p. 11, lines 23-24 (for the first instance); and on page 12, line 9, and p. 43, lines 15-16.

The sub-heading changes made on pages 29 and 30, as well as the first sentence of the second full paragraph on page 32, correct clerical errors, and serves to clarify the identity of the resin components.

Support for Claim 6 is found in Examples 3 and 6, which are presented in Table 1, pages 37-38.

Support for Claim 7 is found in Examples 2, 5, 8, and 11, which are presented in Table 1, pages 37-38.

Support for Claims 8-10 is found in original, now cancelled, Claims 3-5.

Support for the Amendment to the Abstract (pages 45-45) is found in the original Abstract.

Claims 1-2 and 6-10 are now active.